

688072

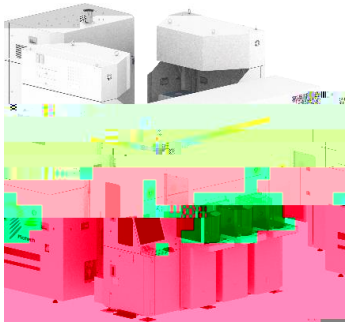
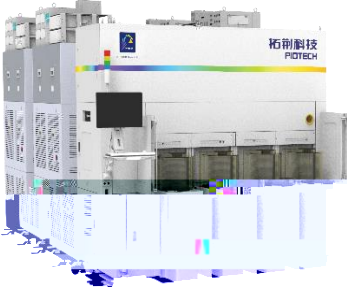
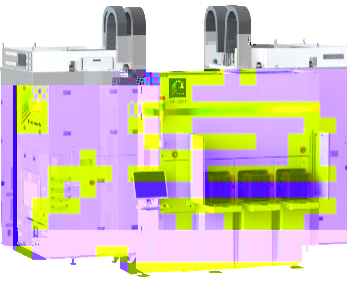
2023

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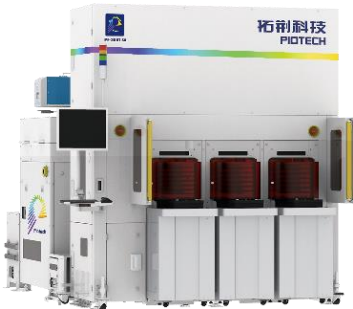
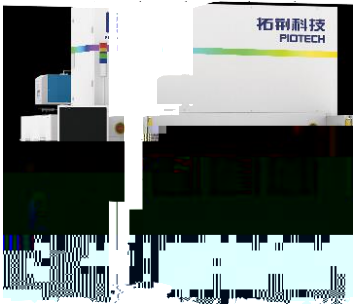
PECVD ALD SACVD HDPCVD

<p>PF-300T pX PF-300T Plus pX</p>		
<p>PF-300T Supra-D PF-300M Supra-D</p>		
<p>NF-300H</p>		<p>TEOS</p> <p>Thick</p>
<p>PF-150T PF-200T</p>		<p>Si C SiO₂ Si N TEOS</p> <p>Si ON</p>

UV Cure

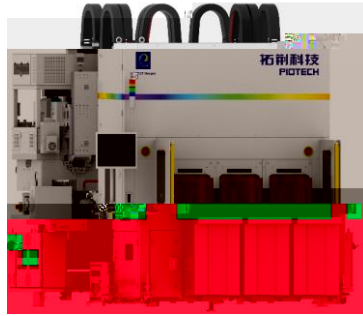
<p>PF-300T Altair</p>		
<p>TS-300 Altair</p>		<p>Al₂O₃</p>

3 SACVD

<p>PF-300T SA</p>		<p>SA TEOS</p>
<p>PF-300T SAF</p>		<p>8 12 SACVD</p>

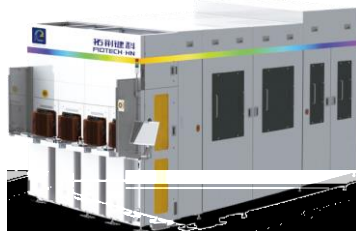
4 HDPCVD

PF-300T
Hesper



5

Di one 300



12

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4

Demo

Demo

5

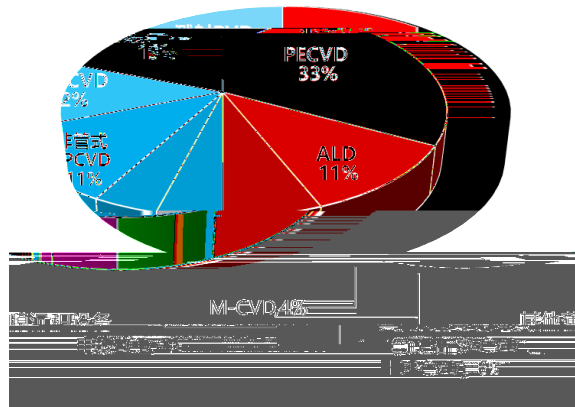
Demo

()

1.

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				2022				
				SEMI	2023			
1,063			1.3%	2023				
			2024					2025
	1,240							
2023				29%	366			
				SEMI	2023			
	90%	960						
				22%	2023			
211								29%
	2023				61			
			CVD	PVD		CVD		PECVD
ALD	SACVD	HDPCVD						
					SEMI		PECVD	
					33%	ALD	11%	SACVD
					6%			HDPCVD



SEMI

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Chi pl et

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18-24

2.

	Gartner		CVD		AMAT		Lam
	TEL		70%				
EV Group		SUSS		TEL			

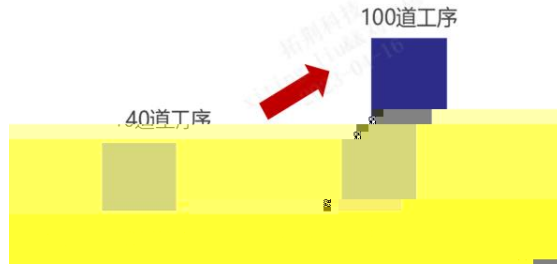
PECVD ALD SACVD HDPCVD

PECVD ALD SACVD HDPCVD

3.

	SEMI		300mm		2025	20%	1,165	2026
	12%	1,305					4	
300								WPM
2023	5.5%	2,960		2024	6.4%		3,000	
200mm				2024		18	2023	
12%		760		2024		13%	860	

	90nm CMOS		40		Fi nFET
100			6	20	



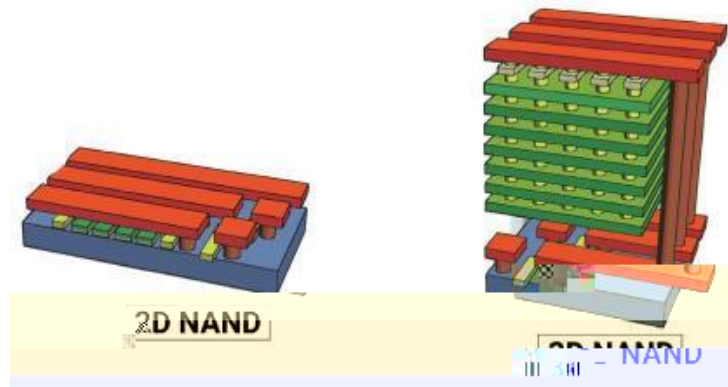
FLASH

2D NAND

3D NAND

3D NAND FLASH

2D NAND 3D NAND

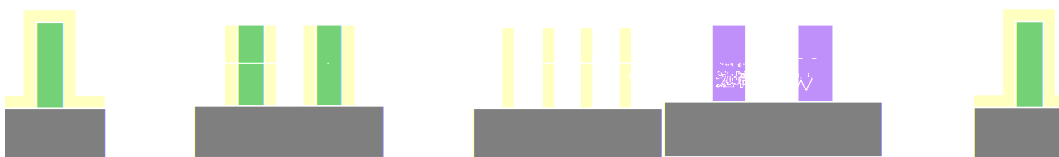


SEMI

ALD

ALD

ALD在多重曝光中的应用



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Micro Bump -

Hybrid Bonding

Al

3

3.1 3

	12,058,443	37,180,198	19.76	37,180,198			0	
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8,302,703 25,600,000 13.60 25,600,000

2,303,775 2,303,775

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